

ABSTRACT

Embodiments herein relate to systems, apparatuses, or processes for an interconnect hub for dies that includes a first side and a second side opposite the first side to couple with three or more dies, where the second side includes a plurality of electrical couplings to electrically couple at least one of the three or more dies to another of the three or more dies to facilitate data transfer between at least a subset of the three or more dies. The three or more dies may be tiled dies.

Fig. 1A